Renesas Electronics America Inc - R5F2L38CCNFP#31 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	68
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 16x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2l38ccnfp-31

1.1.2 Differences between Groups

Table 1.1 lists the Differences between Groups, Table 1.2 lists the Programmable I/O Ports Provided for Each Group, and Table 1.3 lists the LCD Display Function Pins Provided for Each Group. Figures 1.9 to 1.13 show the Pin Assignment for Each Group, and Tables 1.7 to 1.10 list Product Information.
The explanations in the chapters which follow apply to the R8C/L3AC Group only. Note the differences shown below.

Table 1.1 Differences between Groups

Item	Function	R8C/L35C Group	R8C/L36C Group	R8C/L38C Group	R8C/L3AC Group
I/O Ports	Programmable I/O ports	41 pins	52 pins	68 pins	88 pins
	High current drive ports	5 pins	8 pins	8 pins	16 pins
Interrupts	$\overline{\text{INT}}$ interrupt pins	5 pins	8 pins	8 pins	8 pins
	Key input interrupt pins	4 pins	4 pins	8 pins	8 pins
Timer RA	Timer RA output pin	None	1 pin	1 pin	1 pin
Timer RB	Timer RB output pin	None	1 pin	1 pin	1 pin
Timer RD	Timer RD I/O pin	None	None	8 pins	8 pins
Timer RE	Timer RE output pin	None	1 pin	1 pin	1 pin
Timer RG	Timer RG I/O pin	None	None	None	2 pins
	Timer RG output pin	None	None	None	2 pins
A/D Converter	Analog input pin	10 pins	10 pins	16 pins	20 pins
LCD Drive Control Circuit	LCD power supply	3 pins (VL1, VL2, VL4)	4 pins (VL1 to VL4)	4 pins (VL1 to VL4)	4 pins (VL1 to VL4)
	Common output pins	Max. 4 pins	Max. 8 pins	Max. 8 pins	Max. 8 pins
	Segment output pins	Max. 24 pins	Max. 32 pins	Max. 48 pins	Max. 56 pins
Packages		52-pin LQFP	64-pin LQFP	80-pin LQFP	100-pin LQFP/ 100-pin QFP

Note:
1. I/O ports are shared with I/O functions, such as interrupts or timers.
Refer to **Tables 1.11 to 1.13, Pin Name Information by Pin Number**, for details.

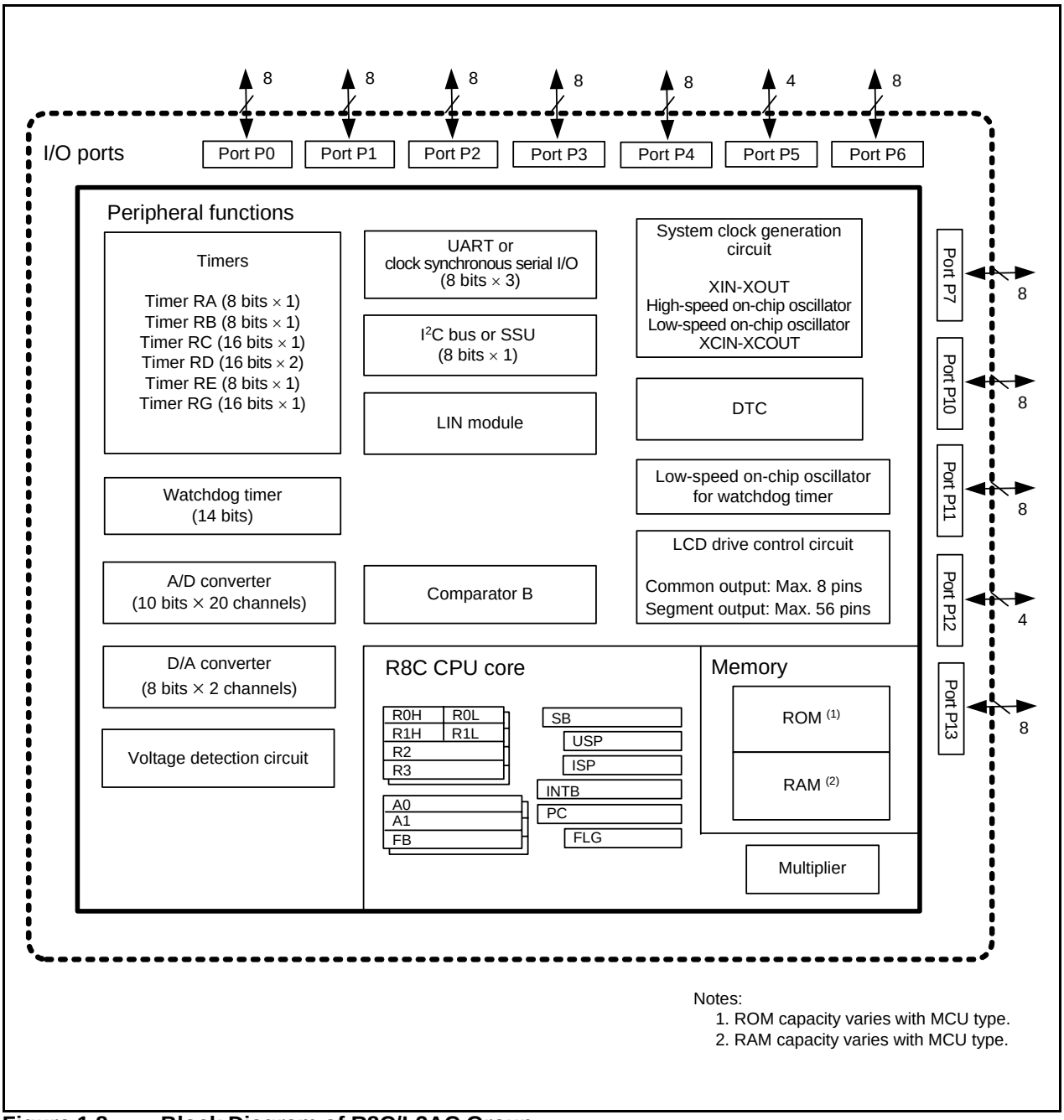
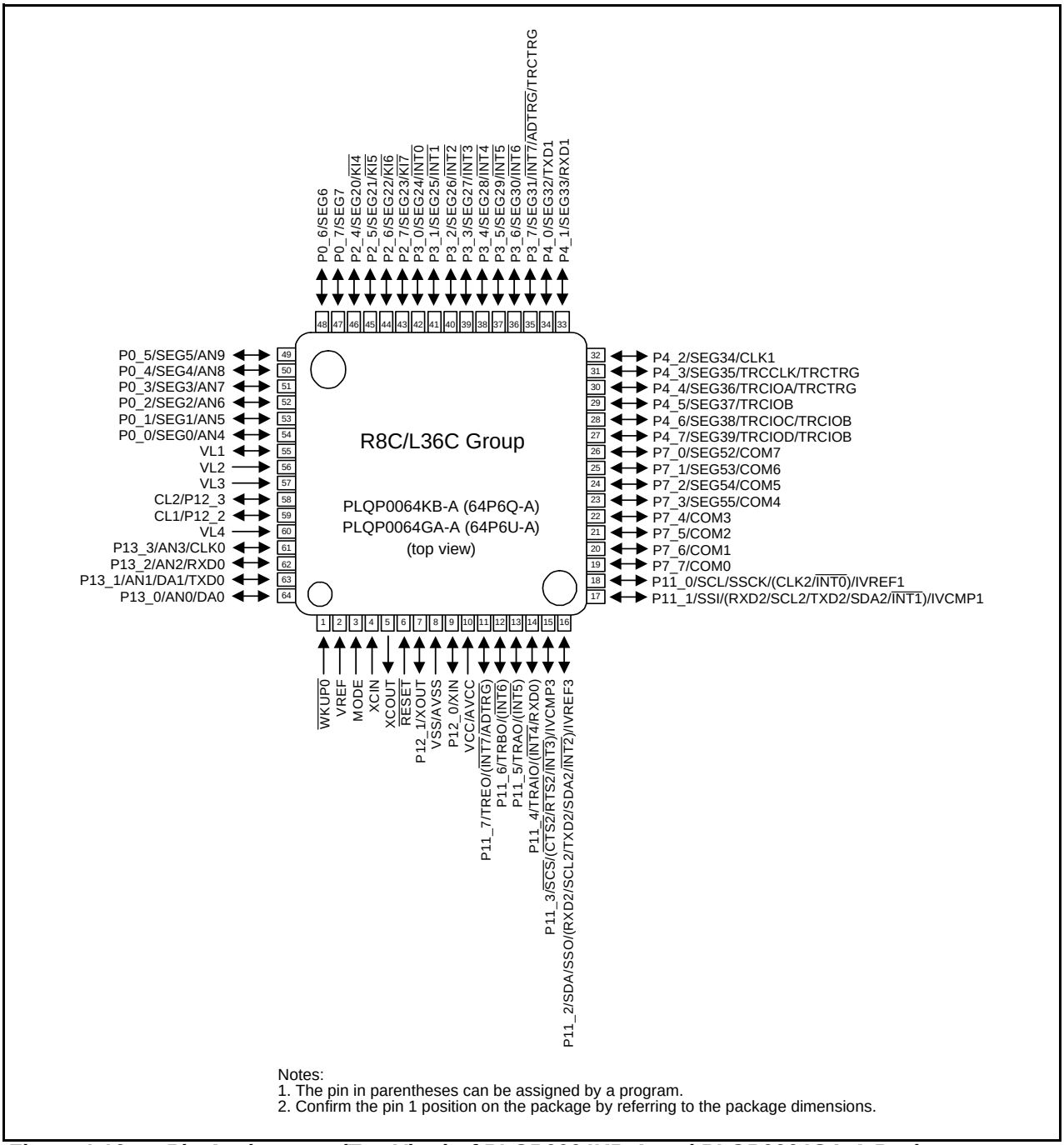


Figure 1.8 Block Diagram of R8C/L3AC Group



Notes:
1. The pin in parentheses can be assigned by a program.
2. Confirm the pin 1 position on the package by referring to the package dimensions.

Figure 1.10 Pin Assignment (Top View) of PLQP0064KB-A and PLQP0064GA-A Packages

1.5 Pin Functions

Tables 1.14 and 1.15 list Pin Functions for R8C/L3AC Group.

Table 1.14 Pin Functions for R8C/L3AC Group (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Driving this pin low resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
Power-off mode exit input	$\overline{\text{WKUP0}}$	I	This pin is provided for input to exit the mode used in power-off mode. Connect to VSS when not using power-off mode.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic oscillator or a crystal oscillator between pins XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	O	
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between pins XCIN and XCOUT. (1) To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
XCIN clock output	XCOUT	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT7}}$	I	$\overline{\text{INT}}$ interrupt input pins.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI7}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Timer RG	TRGCLKA, TRGCLKB	I	Timer RG input pins
	TRGIOA, TRGIOB	I/O	Timer RG I/O pins
Serial interface	CLK0, CLK1, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD1, RXD2	I	Serial data input pins
	TXD0, TXD1, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	$\overline{\text{RTS2}}$	O	Reception control output pin
	SCL2	I/O	I^2C mode clock I/O pin
	SDA2	I/O	I^2C mode data I/O pin

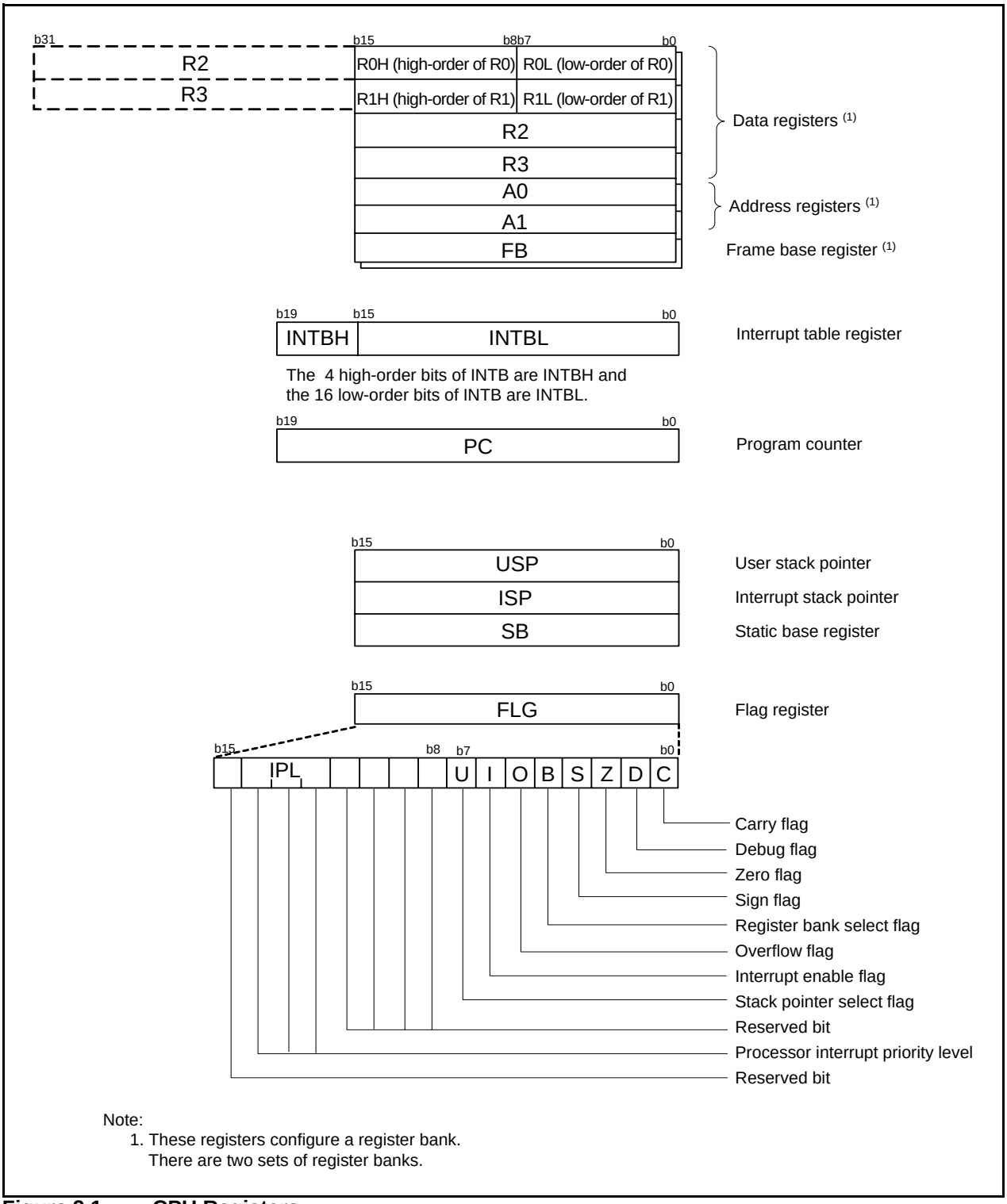
I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register banks.

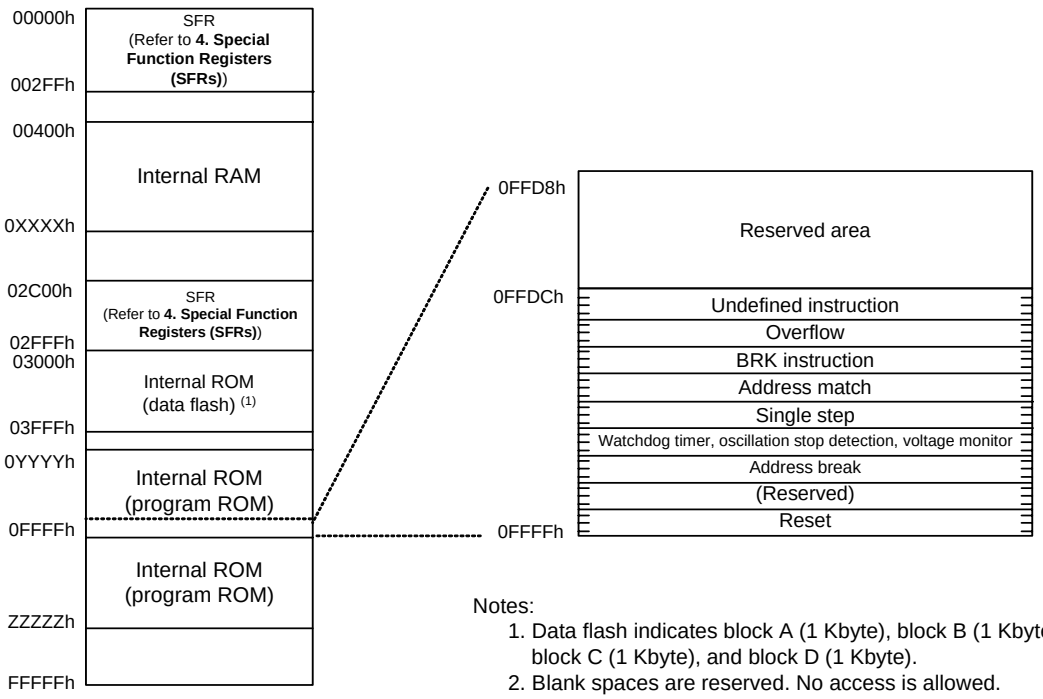


Note:
1. These registers configure a register bank.
There are two sets of register banks.

Figure 2.1 CPU Registers

3. Memory

Figure 3.1 is a Memory Map of each group. Each group has a 1-Mbyte address space from addresses 00000h to FFFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM area is allocated addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. Blank spaces are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh
R5F2L357C***, R5F2L367C***, R5F2L387C***, R5F2L3A7C***	48 Kbytes	04000h	–	6 Kbytes	01BFFh
R5F2L358C***, R5F2L368C***, R5F2L388C***, R5F2L3A8C***	64 Kbytes	04000h	13FFFh	8 Kbytes	023FFh
R5F2L35AC***, R5F2L36AC***, R5F2L38AC***, R5F2L3AAC***	96 Kbytes	04000h	1BFFFh	10 Kbytes	02BFFh
R5F2L35CC***, R5F2L36CC***, R5F2L38CC***, R5F2L3ACC***	128 Kbytes	04000h	23FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map

Table 4.10 SFR Information (10) (1)

Address	Register	Symbol	After Reset
0240h	LCD Display Data Register	LRA48L	XXh
0241h		LRA49L	XXh
0242h		LRA50L	XXh
0243h		LRA51L	XXh
0244h		LRA52L	XXh
0245h		LRA53L	XXh
0246h		LRA54L	XXh
0247h		LRA55L	XXh
0248h			
0249h			
024Ah			
024Bh			
024Ch			
024Dh			
024Eh			
024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh			
025Fh			
0260h			
0261h			
0262h			
0263h			
0264h			
0265h			
0266h			
0267h			
0268h			
0269h			
026Ah			
026Bh			
026Ch			
026Dh			
026Eh			
026Fh			
0270h	LCD Display Control Data Register	LRA0H	XXh
0271h		LRA1H	XXh
0272h		LRA2H	XXh
0273h		LRA3H	XXh
0274h		LRA4H	XXh
0275h		LRA5H	XXh
0276h		LRA6H	XXh
0277h		LRA7H	XXh
0278h		LRA8H	XXh
0279h		LRA9H	XXh
027Ah		LRA10H	XXh
027Bh		LRA11H	XXh
027Ch		LRA12H	XXh
027Dh		LRA13H	XXh
027Eh		LRA14H	XXh
027Fh		LRA15H	XXh

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.15 SFR Information (15) (1)

Address	Register	Symbol	After Reset
2CB0h	DTC Control Data 14	DTCD14	XXh
2CB1h			XXh
2CB2h			XXh
2CB3h			XXh
2CB4h			XXh
2CB5h			XXh
2CB6h			XXh
2CB7h			XXh
2CB8h	DTC Control Data 15	DTCD15	XXh
2CB9h			XXh
2CBAh			XXh
2CBBh			XXh
2CBCh			XXh
2CBDh			XXh
2CBEh			XXh
2CBFh			XXh
2CC0h	DTC Control Data 16	DTCD16	XXh
2CC1h			XXh
2CC2h			XXh
2CC3h			XXh
2CC4h			XXh
2CC5h			XXh
2CC6h			XXh
2CC7h			XXh
2CC8h	DTC Control Data 17	DTCD17	XXh
2CC9h			XXh
2CCAh			XXh
2CCBh			XXh
2CCCh			XXh
2CCDh			XXh
2CCEh			XXh
2CCFh			XXh
2CD0h	DTC Control Data 18	DTCD18	XXh
2CD1h			XXh
2CD2h			XXh
2CD3h			XXh
2CD4h			XXh
2CD5h			XXh
2CD6h			XXh
2CD7h			XXh
2CD8h	DTC Control Data 19	DTCD19	XXh
2CD9h			XXh
2CDAh			XXh
2CDBh			XXh
2CDCh			XXh
2CDDh			XXh
2CDEh			XXh
2CDFh			XXh
2CE0h	DTC Control Data 20	DTCD20	XXh
2CE1h			XXh
2CE2h			XXh
2CE3h			XXh
2CE4h			XXh
2CE5h			XXh
2CE6h			XXh
2CE7h			XXh
2CE8h	DTC Control Data 21	DTCD21	XXh
2CE9h			XXh
2CEAh			XXh
2CEBh			XXh
2CECh			XXh
2CEDh			XXh
2CEEh			XXh
2CEFh			XXh

X: Undefined
Note:
1. Blank spaces are reserved. No access is allowed.

5. Electrical Characteristics

5.1 Absolute Maximum Ratings

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V_{CC}/AV_{CC}	Supply voltage			–0.3 to 6.5	V
V_I	Input voltage	XIN	XIN-XOUT oscillation on (oscillation buffer ON) (1)	–0.3 to 1.65	V
		XIN	XIN-XOUT oscillation on (oscillation buffer OFF) (1)	–0.3 to V_{CC} + 0.3	V
		VL1		–0.3 to VL2	V
		VL2	R8C/L35C	VL1 to VL4	V
			R8C/L36C, R8C/L38C, R8C/L3AC	VL1 to VL3	V
		VL3		VL2 to VL4	V
		VL4		VL3 to 6.5	V
		Other pins		–0.3 to V_{CC} + 0.3	V
V_O	Output voltage	XOUT	XIN-XOUT oscillation on (oscillation buffer ON) (1)	–0.3 to 1.65	V
		XOUT	XIN-XOUT oscillation on (oscillation buffer OFF) (1)	–0.3 to V_{CC} + 0.3	V
		VL1		–0.3 to VL2 (2)	V
		VL2	R8C/L35C	VL1 to VL4	V
			R8C/L36C, R8C/L38C, R8C/L3AC	VL1 to VL3	V
		VL3		VL2 to VL4	V
		VL4		–0.3 to 6.5	V
		CL1, CL2		–0.3 to 6.5	V
		COM0 to COM7		–0.3 to VL4	V
		SEG0 to SEG55		–0.3 to VL4	V
		Other pins		–0.3 to V_{CC} + 0.3	V
P_d	Power dissipation		–40°C ≤ T_{opr} ≤ 85°C	500	mW
T_{opr}	Operating ambient temperature			–20 to 85 (N version) / –40 to 85 (D version)	°C
T_{stg}	Storage temperature			–65 to 150	°C

Notes:
1. For the register settings for each operation, refer to **7. I/O Ports** and **9. Clock Generation Circuit** in the User's Manual: Hardware.
2. The VL1 voltage should be VCC or below.

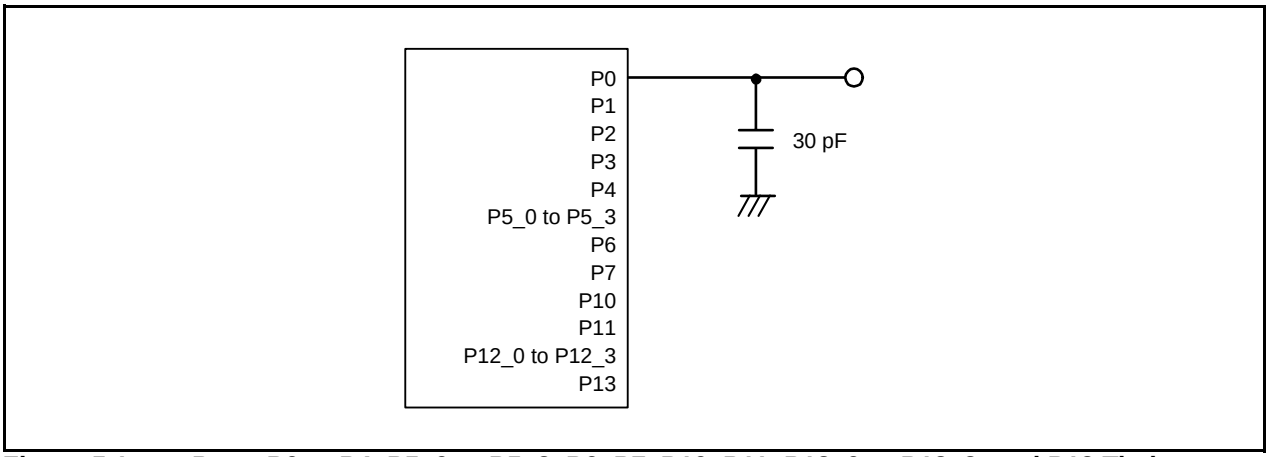


Figure 5.1 Ports P0 to P4, P5_0 to P5_3, P6, P7, P10, P11, P12_0 to P12_3, and P13 Timing Measurement Circuit

5.3 Peripheral Function Characteristics

Table 5.3 A/D Converter Characteristics
(V_{CC}/AV_{CC} = Vref = 2.2 to 5.5 V, V_{SS} = 0 V, and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
—	Resolution		V_{ref} = AV_{CC}		—	—	10	Bit
—	Absolute accuracy (2)	10-bit mode	V_{ref} = AV_{CC} = 5.0 V	AN0 to AN19 input	—	—	±3	LSB
			V_{ref} = AV_{CC} = 3.3 V	AN0 to AN19 input	—	—	±5	LSB
			V_{ref} = AV_{CC} = 3.0 V	AN0 to AN19 input	—	—	±5	LSB
			V_{ref} = AV_{CC} = 2.2 V	AN0 to AN19 input	—	—	±5	LSB
		8-bit mode	V_{ref} = AV_{CC} = 5.0 V	AN0 to AN19 input	—	—	±2	LSB
			V_{ref} = AV_{CC} = 3.3 V	AN0 to AN19 input	—	—	±2	LSB
			V_{ref} = AV_{CC} = 3.0 V	AN0 to AN19 input	—	—	±2	LSB
			V_{ref} = AV_{CC} = 2.2 V	AN0 to AN19 input	—	—	±2	LSB
ϕAD	A/D conversion clock		4.0 ≤ V_{ref} = AV_{CC} ≤ 5.5 V (1)		2	—	20	MHz
			3.2 ≤ V_{ref} = AV_{CC} ≤ 5.5 V (1)		2	—	16	MHz
			2.7 ≤ V_{ref} = AV_{CC} ≤ 5.5 V (1)		2	—	10	MHz
			2.2 ≤ V_{ref} = AV_{CC} ≤ 5.5 V (1)		2	—	5	MHz
—	Tolerance level impedance				—	3	—	kΩ
t_{CONV}	Conversion time	10-bit mode	V_{ref} = AV_{CC} = 5.0 V, ϕAD = 20 MHz		2.2	—	—	µs
		8-bit mode	V_{ref} = AV_{CC} = 5.0 V, ϕAD = 20 MHz		2.2	—	—	µs
t_{SAMP}	Sampling time		ϕAD = 20 MHz		0.8	—	—	µs
I_{Vref}	V_{ref} current		Vcc = 5 V, XIN = f1 = ϕAD = 20 MHz		—	45	—	µA
V_{ref}	Reference voltage				2.2	—	AV_{CC}	V
V_{IA}	Analog input voltage (3)				0	—	V_{ref}	V
OCVREF	On-chip reference voltage		2 MHz ≤ ϕAD ≤ 4 MHz		1.19	1.34	1.49	V

Notes:
1. The A/D conversion result will be undefined in wait mode, stop mode, power-off mode, when the flash memory stops, and in low-current-consumption mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
2. This applies when the peripheral functions are stopped.
3. When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 5.7 Flash Memory (Data flash Block A to Block D) Characteristics (V_{CC} = 2.7 to 5.5 V and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		10,000 (2)	—	—	times
—	Byte program time (program/erase endurance ≤ 1,000 times)		—	160	1500	µs
—	Byte program time (program/erase endurance > 1,000 times)		—	300	1500	µs
—	Block erase time (program/erase endurance ≤ 1,000 times)		—	0.2	1	s
—	Block erase time (program/erase endurance > 1,000 times)		—	0.3	1	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	ms
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		−20 (6)	—	85	°C
—	Data hold time (7)	Ambient temperature = 55 °C	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. −40°C for D version.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

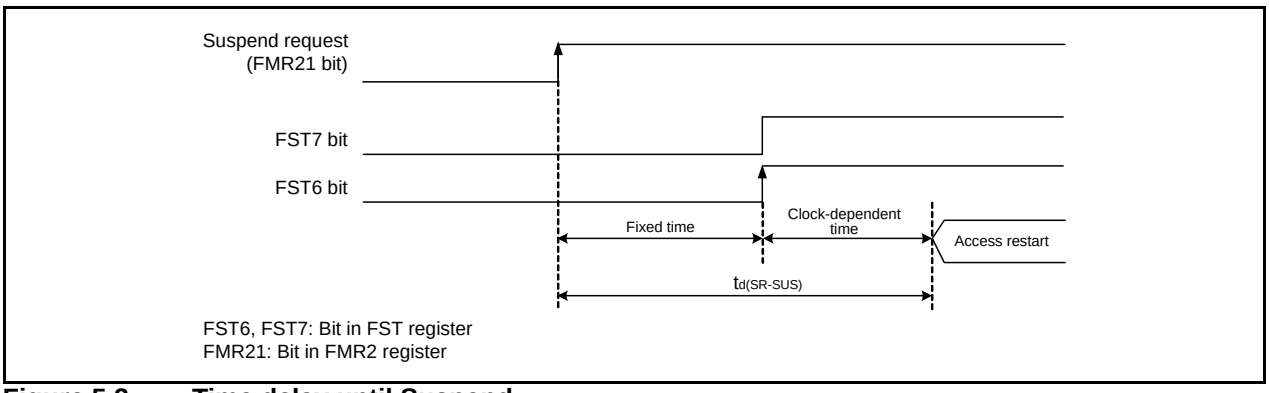


Figure 5.2 Time delay until Suspend

Table 5.12 High-speed On-Chip Oscillator Circuit Characteristics (VCC = 1.8 to 5.5 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	High-speed on-chip oscillator frequency after reset	VCC = 1.8 V to 5.5 V –20°C ≤ Topr ≤ 85°C	38.4	40	41.6	MHz
		VCC = 1.8 V to 5.5 V –40°C ≤ Topr ≤ 85°C	38.0	40	42.0	MHz
	High-speed on-chip oscillator frequency when the FRA4 register correction value is written into the FRA1 register and the FRA5 register correction value into the FRA3 register (1)	VCC = 1.8 V to 5.5 V –20°C ≤ Topr ≤ 85°C	35.389	36.864	38.338	MHz
		VCC = 1.8 V to 5.5 V –40°C ≤ Topr ≤ 85°C	35.020	36.864	38.707	MHz
	High-speed on-chip oscillator frequency when the FRA6 register correction value is written into the FRA1 register and the FRA7 register correction value into the FRA3 register	VCC = 1.8 V to 5.5 V –20°C ≤ Topr ≤ 85°C	30.72	32	33.28	MHz
		VCC = 1.8 V to 5.5 V –40°C ≤ Topr ≤ 85°C	30.40	32	33.60	MHz
—	Oscillation stability time	VCC = 5.0 V, Topr = 25°C	—	0.5	3	ms
—	Self power consumption at oscillation	VCC = 5.0 V, Topr = 25°C	—	400	—	µA

Note:
1. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.13 Low-speed On-Chip Oscillator Circuit Characteristics (VCC = 1.8 to 5.5 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		112.5	125	137.5	kHz
—	Oscillation stability time	VCC = 5.0 V, Topr = 25°C	—	30	100	µs
—	Self power consumption at oscillation	VCC = 5.0 V, Topr = 25°C	—	3	—	µA
fOCO-WDT	Low-speed on-chip oscillator frequency for the watchdog timer		60	125	250	kHz
—	Oscillation stability time	VCC = 5.0 V, Topr = 25°C	—	30	100	µs
—	Self power consumption at oscillation	VCC = 5.0 V, Topr = 25°C	—	2	—	µA

Table 5.14 Power Supply Circuit Characteristics (VCC = 1.8 to 5.5 V, VSS = 0 V, and Topr = 25°C, unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during power-on (1)		—	—	2000	µs

Note:
1. Waiting time until the internal power supply generation circuit stabilizes during power-on.

Table 5.15 LCD Drive Control Circuit Characteristics (VCC = 1.8 to 5.5 V, VSS = 0 V, and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
VLCD	LCD power supply voltage	VLCD = VL4	2.2	—	5.5	V
VL3	VL3 voltage		VL2	—	VL4	V
VL2	VL2 voltage	R8C/L35C	VL1	—	VL4	V
		R8C/L36C, R8C/L38C, R8C/L3AC	VL1	—	VL3	V
VL1	VL1 voltage		1	—	VL2 (3)	V
—	VL1 internally-generated voltage accuracy (1)		Setting voltage –0.2	Setting voltage	Setting voltage +0.2	V
f(FR)	Frame frequency		50	—	180	Hz
ILCD	LCD drive control circuit current		—	(Note 2)	—	µA

Notes:
1. The voltage is selected with bits LVLS0 to LVLS3 in the LCR1 register.
2. Refer to **Table 5.18 DC Characteristics (2)**, **Table 5.20 DC Characteristics (4)**, and **Table 5.22 DC Characteristics (6)**.
3. The VL1 voltage should be VCC or below.

Table 5.16 Power-Off Mode Characteristics (VCC = 2.2 to 5.5 V, VSS = 0 V, and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	Power-off mode operating supply voltage		2.2	—	5.5	V

Table 5.18 DC Characteristics (2) [4.0 V ≤ Vcc ≤ 5.5 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition								Standard			Unit
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ. (3)	Max.	
			XIN (2)	XCIN	High-Speed (fOCO-F)	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	7.0	15	mA
			16 MHz	Off	Off	125 kHz	No division	—		—	5.6	12.5	mA
			10 MHz	Off	Off	125 kHz	No division	—		—	3.6	—	mA
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	3.0	—	mA
			16 MHz	Off	Off	125 kHz	Divide-by-8	—		—	2.2	—	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz	125 kHz	No division	—		—	7.0	15	mA
			Off	Off	20 MHz	125 kHz	Divide-by-8	—		—	3.0	—	mA
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRD = 1 MSTTRC = 1 MSTTRG = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0		—	90	400	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0		—	100	400	µA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM	—	55	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	100	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	90	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode	LCD drive control circuit (4) When external division resistors are used	—	7	—	µA
										LCD drive control circuit (5) When the internal voltage multiplier is used	—	12	—	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode		—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off		—	2.0	5.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off		—	15	—	µA
		Power-off mode	Off	Off	Off	Off	—	—	Topr = 25°C		—	0.02	0.2	µA
			Off	Off	Off	Off	—	—	Topr = 85°C		—	0.4	—	µA

Notes:
1. Vcc = 4.0 V to 5.5 V, single chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. Vcc = 5.0 V
4. VLCD = Vcc, external division resistors are used for VL4 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open. The standard value does not include the current that flows through external division resistors.
5. The internal voltage multiplier is used, bits LVLS3 to LVLS0 in the LCR1 register = 1011b, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.

Table 5.19 DC Characteristics (3) [2.7 V ≤ Vcc < 4.0 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Port P10, P11 (1)	I_{OH} = –5 mA	V_{CC} – 0.5	—	V_{CC}	V
		Other pins	I_{OH} = –1 mA	V_{CC} – 0.5	—	V_{CC}	V
		XOUT	I_{OH} = –200 μA	1.0	—	—	V
V_{OL}	Output “L” voltage	Port P10, P11 (1)	I_{OL} = 5 mA	—	—	0.5	V
		Other pins	I_{OL} = 1 mA	—	—	0.5	V
		XOUT	I_{OL} = 200 μA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{INT4}$, $\overline{INT5}$, $\overline{INT6}$, $\overline{INT7}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, $\overline{KI4}$, $\overline{KI5}$, $\overline{KI6}$, $\overline{KI7}$, TRAIO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRGCLKA, TRGCLKB, $\overline{TRGIOA}$, TRGIOB, $\overline{ADTRG}$, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO		0.05	0.4	—	V
		$\overline{RESET}$, $\overline{WKUP0}$		0.1	0.8	—	V
I_{IH}	Input “H” current		VI = 3.0 V, V_{CC} = 3.0 V	—	—	5.0	μA
I_{IL}	Input “L” current		VI = 0 V, V_{CC} = 3.0 V	—	—	–5.0	μA
R_{PULLUP}	Pull-up resistance		VI = 0 V, V_{CC} = 3.0 V	30	100	170	kΩ
R_{fXIN}	Feedback resistance	XIN		—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN		—	14	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode	1.8	—	—	V

Note:
1. This applies when the drive capacity of the output transistor is set to High by registers P10DRR and P11DRR. When the drive capacity is set to Low, the value of any other pin applies.

Table 5.22 DC Characteristics (6) [1.8 V ≤ Vcc < 2.7 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition								Standard			Unit
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other		Min.	Typ. (3)	Max.	
			XIN (2)	XCIN	High-Speed (fOCO-F)	Low-Speed								
Icc	Power supply current (1)	High-speed clock mode	5 MHz	Off	Off	125 kHz	No division	—			—	2.2	—	mA
			5 MHz	Off	Off	125 kHz	Divide-by-8	—			—	0.8	—	mA
		High-speed on-chip oscillator mode	Off	Off	5 MHz	125 kHz	No division	—			—	2.5	10	mA
			Off	Off	5 MHz	125 kHz	Divide-by-8	—			—	1.7	—	mA
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRD = 1 MSTTRC = 1 MSTTRG = 1			—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0			—	90	300	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0			—	90	400	µA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM		—	45	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation		—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off		—	4	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode	LCD drive control circuit (4) When external division resistors are used	—	4	—	µA
										LCD drive control circuit (5) When the internal voltage multiplier is used	—	11	—	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode		—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off		—	2.0	5.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off		—	13	—	µA
		Power-off mode	Off	Off	Off	Off	—	—	Topr = 25°C		—	0.02	0.2	µA
			Off	Off	Off	Off	—	—	Topr = 85°C		—	0.3	—	µA

Notes:
1. Vcc = 1.8 V to 2.7 V, single chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. Vcc = 2.2 V
4. VLCD = Vcc, external division resistors are used for VL4 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.The standard value does not include the current that flows through external division resistors.
5. The internal voltage multiplier is used, bits LVLS3 to LVLS0 in the LCR1 register = 1011b, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.

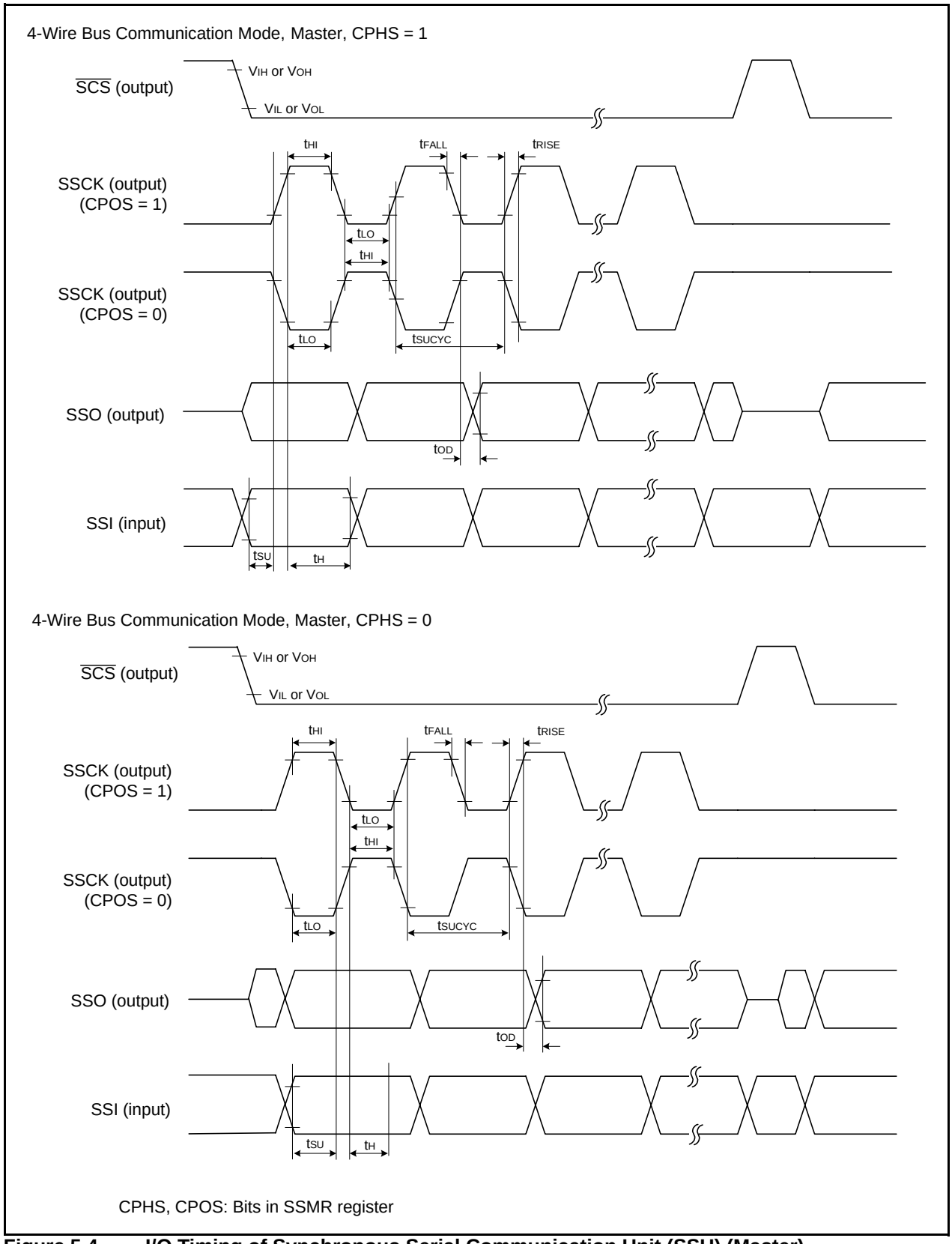


Figure 5.4 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

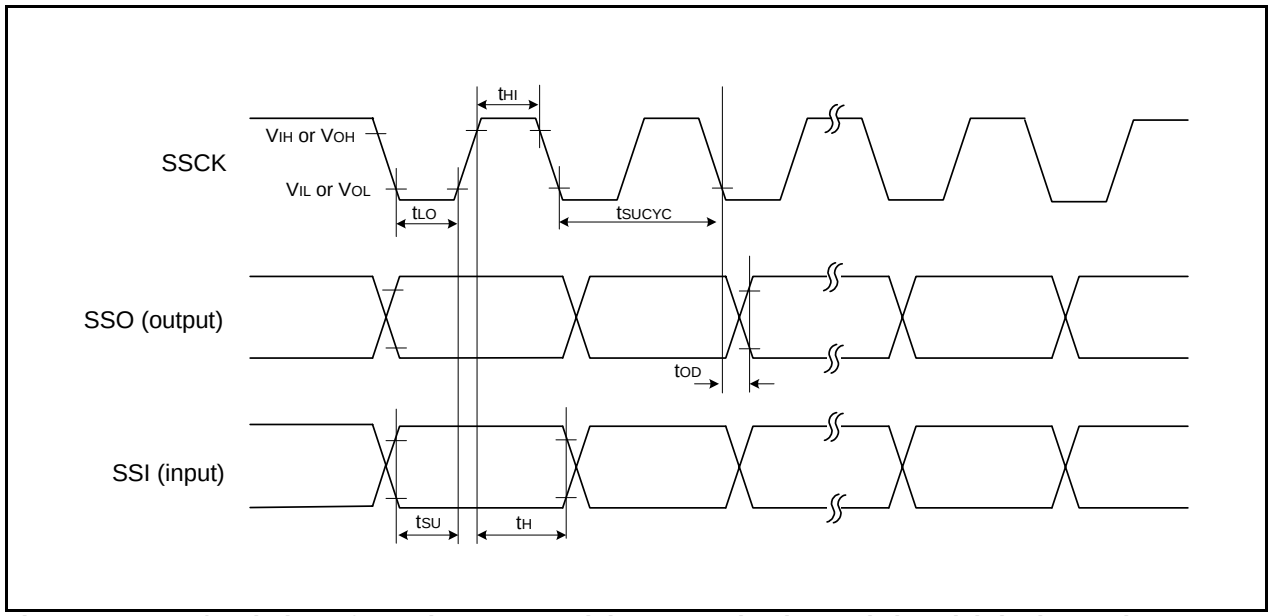


Figure 5.6 I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)

REVISION HISTORY	R8C/L35C Group, R8C/L36C Group, R8C/L38C Group, R8C/L3AC Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.10	Oct 30, 2009	—	First Edition issued
0.20	Apr 15, 2011	6	Table 1.6 Function deleted, Current consumption revised
		7	1.2 “of R8C/Lx Series” → “for Each Group”
		7 to 10	Tables 1.7 to 1.10 revised
		24	Table 1.15 “Voltage detection circuit” deleted
		29	4. Special Function Registers (SFRs) “The description offered in this chapter is based on the R8C/L3AC Group.” added
		45 to 68	5. Electrical Characteristics added
1.00	Jun 25, 2010	—	“Preliminary” and “Under development” deleted
		1	1.1 revised
		7 to 10	Tables 1.7 to 1.10 revised
		45	Tables 5.1 Note 2 added
		55	Table 5.15 Note 3 added
		69 to 72	Package Dimensions revised
1.01	Apr 15, 2011	2	Table 1.1 revised
		3	Table 1.2 Note 2, Table 1.3 Note 1 revised
		6	Table 1.6 “Flash Memory” revised
		11 to 14	Figure 1.5 to Figure 1.8 revised
		20 to 22	Table 1.11 to Table 1.13 “Voltage Detection Circuit” deleted
		23, 24	Table 1.14 and Table 1.15 title “for R8C/L3AC Group” added
		28	3. “The internal ROM ... with address 0FFFFh.” deleted
		38 to 40	Table 4.10 to Table 4.12 “0248h to 026Fh”, “02A8h to 02BFh”, “02C0h to 02CFh” revised
		48	Table 5.3 “t_{CONV}”, “t_{SAMP}” revised
		57, 59, 61	Table 5.18, Table 5.20, Table 5.22 “High-Speed” → “High-Speed (fOCO-F)”

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